Docket No.:

MRE-0063

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that: My residence, post office and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled DEVICE FOR COMPENSATING FOR HEAT DEVIATION IN A MODULAR IC TEST HANDLER, the specification of which [] was filed on _____ as Application Serial No. _ and was [X] is attached hereto ____ (if applicable) I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56(a). I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365 (b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or of any PCT international application having a filing date before that of the application on which priority is claimed. Foreign Filing Date Prior Foreign Application(s): Month/Day/Year Number Country P 2002-87797 Korea I hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below. Filing Date (Month/Day/Year) Application Number(s): I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s), or 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application. Prior U. S. Application Filing Date (Month/Day/Year) Parent Patent Number (if applicable) or PCT Parent Number I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are

believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements

may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186; Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372; John C. Eisenhart, Registration No. 38,128; Donald R. McPhail, Registration No. 35,811; Carol L. Druzbick, Registration No. 40,287; Anthony H. Nourse, Registration No. 46,121; Laura L. Lee, Registration No. 48,752; Rene A. Vazquez, Registration No. 38,647; Timothy M. Speer, Registration No. 47,355; Samuel W. Ntiros, Registration No. 39,318; Mark R. Buscher, Registration No. 35,006; Daniel H. Sherr, Registration No. 46,425; Tyler S. Brown, Registration No. 36,465; John L. Ciccozzi, Registration No. 48,984; and Steven J. Helmer, Registration No. 40,475; and Mark E. Olds, Registration No. 46,507, all of

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